

ABSTRACT OF THE DISCLOSURE

A method for making a semiconductor device includes mounting a die on a die-mounting substrate, providing an interposer on the substrate, forming a 5 conductive strip that is laid on the interposer and that is electrically connected to a bonding pad of the die and to a contact of the substrate, forming an encapsulant layer on the interposer, and forming a solder bump that is electrically connected to the 10 conductive strip and protrudes outwardly from the encapsulant layer.